



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2024-04-01
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Material Declaration champion	<b>Representative Title</b>	Material Declaration champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32L4Q5CGT6	725B*471XXXZ	A	998Z	2024-04-01
	Amount	UoM	Unit type	ST ECOPACK Grade
	180.91	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	7x7	48	L bend	
Comment	Package : 5B LQFP 48 7x7x1.4 1 0110596			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-14th June 2023				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	725B*471XXXZ				6000001.0	1000002.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	17.868	mg	#N/A	die	Silicon (Si)	7440-21-3		17.187	mg	961887	95006
				#N/A	metallization	Aluminium (Al)	7429-90-5		0.033	mg	1847	182
				#N/A	metallization	Copper (Cu)	7440-50-8		0.289	mg	16174	1598
				#N/A	metallization	Cobalt (Co)	7440-48-4		0.001	mg	56	6
				#N/A	metallization	Tantalum (Ta)	7440-25-7		0.093	mg	5205	514
				#N/A	metallization	Titanium (Ti)	7440-32-6		0.003	mg	168	17
				#N/A	metallization	Tungsten (W)	7440-33-7		0.002	mg	112	11
				supplier	Passivation	Silicon Nitride	12033-89-5		0.073	mg	4086	404
				#N/A	Passivation	Silicon Oxide	7631-86-9		0.187	mg	10466	1034
Glue Epoxy (3230)	M-011 Other inorganic materials	2.393	mg	Supplier	Metals	Silver	7440-22-4		1.950	mg	815000	10780
				Supplier	Plastics/polymers	2,2'-(Methylenebis(phenyleneoxymethylene))	39817-09-9		0.072	mg	30000	397
				Supplier	Organic Compounds	Dihydro-3-(tetrapropenyl)furan-2,5-dione	26544-38-7		0.072	mg	30000	397
				Supplier	Organic Compounds	Epoxy resin	Proprietary		0.072	mg	30000	397
				Supplier	Organic Compounds	Dodecylloxirane	3234-28-4		0.072	mg	30000	397
				Supplier	Organic Compounds	Hexahydromethylphthalic anhydride	25550-51-0		0.072	mg	30000	397
				Supplier	Organic Compounds	Epoxy resin modifier	Proprietary		0.072	mg	30000	397
				Supplier	Metallic compounds	Copper oxide	1317-38-0		0.012	mg	5000	66
				Encapsulation (EME-G631SHQ)	M-011 Other inorganic materials	108.031	mg	Supplier	Plastics/polymers	Epoxy Resin A	Proprietary	
Supplier	Plastics/polymers	Epoxy Resin B	Proprietary						2.269	mg	21000	12541
Supplier	Plastics/polymers	Phenol Resin	Proprietary						6.050	mg	56000	33442
Supplier	Glass	Silica(Amorphous)A	60676-86-0						84.313	mg	780450	466062
Supplier	Glass	Silica(Amorphous)B	7631-86-9						12.458	mg	115320	68866
Supplier	Non-metals	Carbon Black	1333-86-4		0.673	mg	6230	3720				
Bonding Wire (Au)	Bonding Wire	0.535	mg	Supplier	Metals	Gold	7440-57-5		0.535	mg	1000000	2955
Plating anode (Sn)	M-011 Other inorganic materials	1.078	mg	Supplier	Metals	Tin	7440-31-5		1.078	mg	1000000	5961
Leadframe (C194 + Ag)	Copper & its alloys	51.000	mg	Supplier	Metals	Copper	7440-50-8		49.582	mg	972200	274079
				Supplier	Metals	Iron	7439-89-6		1.168	mg	22900	6456
				Supplier	Metals	Zinc	7440-66-6		0.077	mg	1500	423
				Supplier	Non-Metals	Phosphorus	7723-14-0		0.015	mg	300	85
Supplier	Metals	Silver	7440-22-4		0.158	mg	3100	874				